



Final Product/Process Change Notification
 Document #:FPCN26191XA
 Issue Date:06 Oct 2025

Title of Change:	Material Change – Addition of KHG300L Mold Compound for SOT23 Package at onsemi Leshan, China	
Proposed First Ship date:	13 Jan 2026 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact	
Marking of Parts/ Traceability of Change:	Affected parts with this change will be identified by date code	
Change Category:	Assembly Change	
Change Sub-Category(s):	Material Change	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Leshan, China	None	
Description and Purpose:		
The Final notification is to inform customers of an upcoming mold type qualification for package SOT23 MOSFET in Leshan onsemi.		
The change is as described in the table below.		
	From	To
Mold Compound	GR640	GR640 or KHG300L
There is no product marking change as a result of this change.		



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Reliability Data Summary:

QV DEVICE NAME: BSS123LT1G

RMS: L92302

PACKAGE: SOT23

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias 80% of rated V or 100V max	192hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	-	0/30
Solderability	JSTD002	Ta = 245°C, 5 sec	-	0/45
Physical Dimension	JESD22-B120		-	0/15

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NTR1P02LT3G	BSS123LT1G
NTR2101PT1G	BSS123LT1G
NTR5198NLT1G	BSS123LT1G
NTR4503NT1G	BSS123LT1G
NTR4502PT1G	BSS123LT1G
NTR4501NT1G	BSS123LT1G
NTR4171PT1G	BSS123LT1G
NTR4170NT1G	BSS123LT1G
NTR4101PT1H	BSS123LT1G



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MGSF2N02ELT1G	BSS123LT1G
MGSF1N03LT1G	BSS123LT1G
MGSF1N02LT1G	BSS123LT1G
BSS138K	BSS123LT1G
NTR1P02LT1G	BSS123LT1G
NTR4101PT1G	BSS123LT1G
NTR3C21N2T3G	BSS123LT1G
NTR3C21N2T1G	BSS123LT1G
NTR5103NT1G	BSS123LT1G
NTR4003NT3G	BSS123LT1G
2N7002ET7G	BSS123LT1G
2N7002ET1G	BSS123LT1G
2N7002KT1G	BSS123LT1G
2N7002KT7G	BSS123LT1G
2N7002LT1G	BSS123LT1G
2N7002LT3G	BSS123LT1G
BSS84LT1G	BSS123LT1G
BSS123LT1G	BSS123LT1G
BSS138LT1G	BSS123LT1G
BSS138LT3G	BSS123LT1G
MMBF170LT1G	BSS123LT1G
MMBF0201NLT1G	BSS123LT1G
NTR5105PT1G	BSS123LT1G
NTR4003NT1G	BSS123LT1G
NTR0202PLT1G	BSS123LT1G
NTR1P02T1G	BSS123LT1G